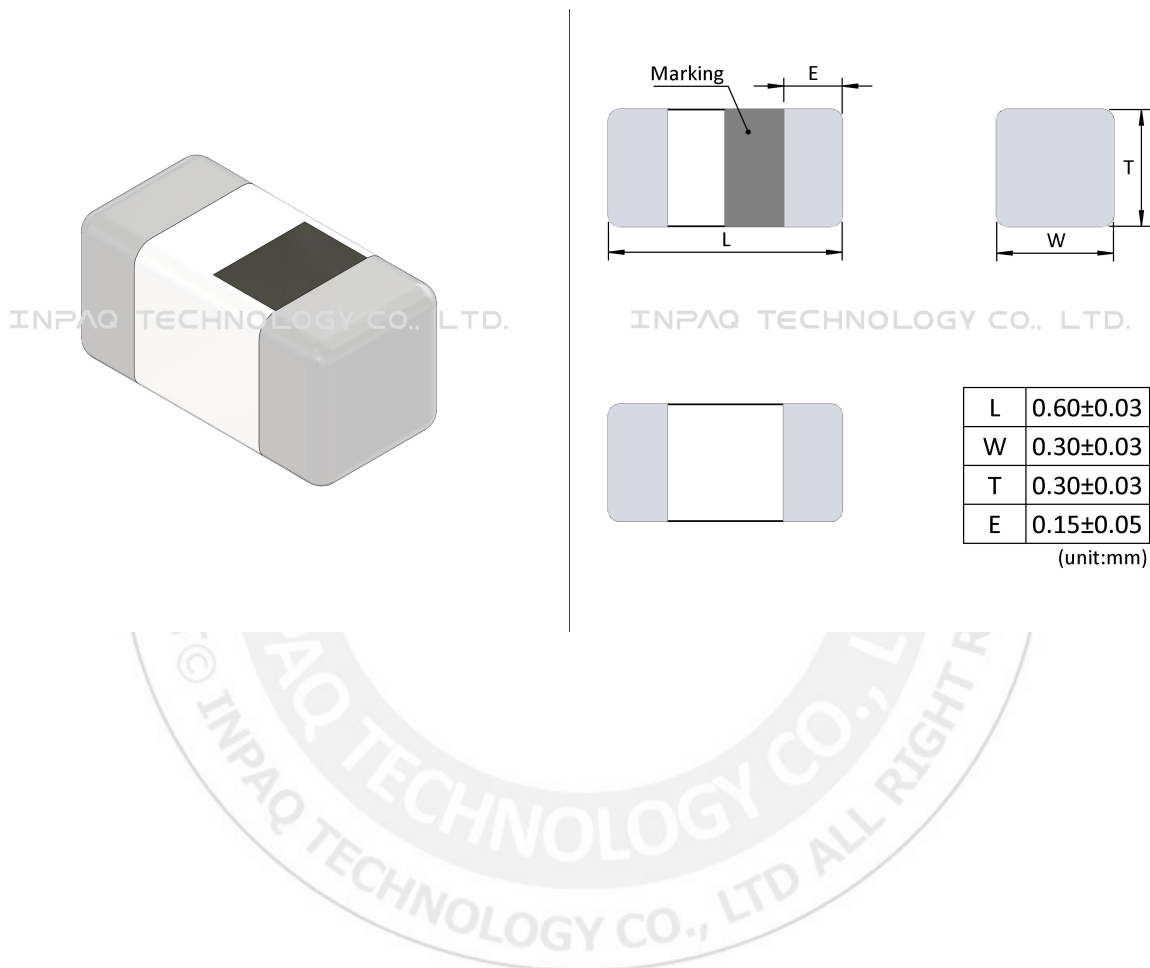


MCI0603TG1N5_HBP



Appearance & Shape



注意 NOTICE: All Specifications are subject to change without notice.

Page 1/3

1. 本文件由 INPAQ 佳邦科技網站下載，若規格變更及停產，請於訂購時確認，恕不另行通知。
2. 本文件僅說明參考標準規格，如需訂購，請依實際核准所需規格進行申辦。

Specification

L size(mm)	0.6±0.03
W size(mm)	0.3±0.03
T size(mm)	0.3±0.03
Size code Inch(mm)	0201(0603)
Inductance(nH)	1.5
Tolerance	B(±0.1nH), C(±0.2nH)
Test Frequency(MHz)	500
DCR(Ω) Max.	0.15
Irms(mA) Max.	600
Q Value (Min.)	12
SRF(MHz) Min.	13500
Operating Temperature range(including self-temperature rising) °C	-55~+125

注意 NOTICE: All Specifications are subject to change without notice.

Page 2/3

1. 本文件由 INPAQ 佳邦科技網站下載，若規格變更及停產，請於訂購時確認，恕不另行通知。
2. 本文件僅說明參考標準規格，如需訂購，請依實際核准所需規格進行申辦。

Notices

- Particular ceramic material and coil structure provide high frequency application range up to 10GHz.
- Small size and low profile.
- Available in various sizes.
- Excellent solderability and heat resistance.

Packing

Packing Reel(Inch)	Packaging type	Standard package quantity(PCS)	Piece weight(gram)	MSL Level
7	Paper type	15000	0.00018	1

注意 NOTICE: All Specifications are subject to change without notice.

Page 3/3

1. 本文件由 INPAQ 佳邦科技網站下載，若規格變更及停產，請於訂購時確認，恕不另行通知。
2. 本文件僅說明參考標準規格，如需訂購，請依實際核准所需規格進行申辦。